

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5388	(@ad<"20000816") and (((substrate or board or interpser or pwb or pcb) and (wire or wires)) with (aperture or cavity or hole or opening or via)) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:57
L2	1	("6335571").PN.	USPAT; USOCR	OR	OFF	2005/10/03 07:56
L3	837	L1 and (encapsulate or encapsulating or encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 08:01
L4	2004	L1 and (encapsulate or encapsulating or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 08:01
L5	123	L4 and (laser same (encapsulate or encapsulating or encapsulant or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 08:03
L6	5426	(@ad<"20000816") and (((substrate or board or interpser or pwb or pcb) and (wire or wires or wirebond or (wire adj bond))) with (aperture or cavity or hole or opening or via)) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 08:02
L7	123	L6 and (laser same (encapsulate or encapsulating or encapsulant or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 08:09
L8	339	(laser and (sink or spreader)) same (encapsulate or encapsulating or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:17
L9	93	L8 and (@ad<"20000816") and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:28

L10	447	laser with ((remove or removal) and (encapsulate or encapsulating or encapsulant or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:03
L11	98	L10 and (@ad<"20000816") and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:05
L12	320	laser with ((drill or drilling) and (encapsulate or encapsulating or encapsulant or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:03
L13	66	L12 and (@ad<"20000816") and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:09
L14	6143	((@ad<"20000816") and (((tape or polyimide or TAB or substrate or board or interpsr or pwb or pcb) and (wire or wires)) with (aperture or cavity or hole or opening or via)) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:17
L15	47	L14 and (((remove or removal or etch or polish or cmp) and (sink or spreader)) same (encapsulate or encapsulating or encapsulant or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:52
L16	47	L15 and (wire or wires)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:19
L17	2526913	LOC and ((sink or spreader) same (encapsulate or encapsulating or encapsulant or epoxy)) nd (wire or wires)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:26

L18	17594	L17 and (tab or tape or polyimide) and (sink or spreader or dissipation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:26
L19	93	LOC and ((sink or spreader) same (encapsulate or encapsulating or encapsulant or epoxy)) and (wire or wires)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:26
L20	87	L19 and (tab or tape or polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:26
L21	34	L20 and (@ad<"20000816")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:49
L22	1	("20020173070").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 09:49
L23	258	438/122.ccls. and ((remove or removal or etch or polish or cmp) and (sink or spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:52
L24	1	438/122.ccls. and ((remove or removal or etch or polish or cmp) with (encapsulant or encapsulate or epoxy)) and (sink or spreader)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:53
L25	2	257/707-708.ccls. and ((remove or removal or etch or polish or cmp) with (encapsulant or encapsulate or epoxy)) and (sink or spreader)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:53
L26	1	(@ad<"20000816") and (chip or die) and (laser same decapsulation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:58